Freescale Semiconductor

MPL015A2 Rev 1, 12/2010

Miniature I²C Digital Barometer

The MPL015A2 is an absolute pressure sensor with digital output for low cost applications. A miniature 5 x 3 x 1.2 mm LGA package ideally suits it for portable electronics and space constrained applications. Low current consumptions of 5 μ A during Active mode and 0.06 μ A during Shutdown (Sleep) mode target battery and other low-power applications. A wide operating temperature range from -40°C to +105°C fits demanding environmental requirements.

MPL015A2 employs a MEMS pressure sensor with a conditioning IC to provide accurate pressure measurement from 50 to 115 kPa. An integrated ADC provides digitized temperature and pressure sensor outputs via an I²C port. Calibration Data is stored in internal ROM. Utilizing raw sensor output, the host microcontroller executes a compensation algorithm to render *Compensated Absolute Pressure*.

The MPL015A2 pressure sensor's small form factor, low power capability, precision, and digital output optimize it for barometric measurement applications.

Features

- Digitized pressure and temperature information together with programmed calibration coefficients for host micro use.
- Factory Calibrated
- 50 kPa to 115 kPa Absolute Pressure
- 1 kPa Accuracy
- 2.375 V to 5.5 V Supply
- Integrated ADC
- I²C Interface
- Monotonic Pressure and Temperature Data Outputs
- Surface Mount RoHS Compliant Package

MPL015A2 50 to 115 kPa

Application Examples

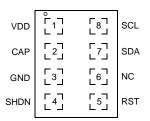
- Barometry (portable and desk-top)
- Altimeters
- Weather Stations
- Hard Disk-Drives (HDD)
- Industrial Equipment
- · Health Monitoring
- · Air Control Systems

ORDERING INFORMATION									
Device Name	Package Options	Case No.	# of Ports			Pressure Type			Digital
Device Name Fackage Options		Case No.	None	Single	Dual	Gauge	Differential	Absolute	Interface
MPL015A2T1	Tape & Reel	2015	•					•	I ² C

LGA PACKAGE



MPL015A2 5.0 mm X 3.0 mm X 1.2 mm MAX



PIN CONNECTIONS

Pin Description

PIN	NAME	FUNCTION
1	VDD	VDD Power Supply Connection.
2	CAP	External Capacitor
3	GND	Ground
4	SHDN	Shutdown (Sleep): Connect to GND to disable the device.
5	RST	Reset: Drive line low to disable I ² C communications.
6	NC	NC: No connection.
7	SDA ⁽¹⁾	SDA: Serial data I/O line.
8	SCL ⁽¹⁾	I ² C Serial Clock Input.

^{1.} Use 4.7k pull-up resistors for I²C communication.



Maximum Ratings

Operating Characteristics

 $(V_{DD} = 2.375 \text{ V} \text{ to } 5.5 \text{ V}, T_A = -40 ^{\circ}\text{C} \text{ to } +105 ^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at V+ = 3.3 V, $T_A = +25 ^{\circ}\text{C}$.

Ref	Parameters	Symbol	Conditions	Min	Тур	Max	Units	
1	Operating Supply Voltage	V_{DD}		2.375	3.3	5.5	V	
2	Supply Current I _{DD}		Shutdown (SHDN = GND) @ 25°C	_	0.06	1	μΑ	
			Standby	_	3.5	10	μΑ	
			Average – at one measurement per second	_	5	6	μΑ	
Press	ure Sensor							
3	Range			50	_	115	kPa	
4	Resolution			_	0.15	_	kPa	
5	Accuracy		@ 25°C	_	±1	_	kPa	
6	Accuracy Change over Temperature			_	±0.125	_	kPa/ºC	
7	Power Supply Rejection		Typical operating circuit at DC	_	0.1	_	kPa/V	
			100 mV p-p 217 Hz square wave plus 100 mV pseudo random noise with 10 MHz bandwidth.	_	0.1	_	kPa	
8	Conversion Time (Start Pressure Convert)	tcp	Time between start convert command and data available in the Pressure register	_	0.6	0.7	ms	
Temp	erature Sensor	•						
9	Range			-40	_	105	°C	
10	Conversion Time (Start Temperature Convert)	tct	Time between start convert command and data available in the Temperature register	_	0.6	0.7	ms	
11	Conversion Time (Start Both Convert)	tcb	Time between start convert command and data available in the Pressure and Temperature registers	_	0.8	1	ms	
12	Resolution		Temperature ADC is 472 counts @ 25°C	_	-5.35	_	counts/°C	
I ² C I/C	Stages: SCL, SDA	l .			1			
13	SCL Clock Frequency	f _{SCL}		_	_	400	KHz	
14	Low Level Input Voltage	VIL		_	_	0.3V _{DD}	V	
15	High Level Input Voltage	VIH		0.7V _{DD}	_	_	V	
I ² C Ou	ıtputs: SDA	ı			1	ı		
16	Data Setup Time	t _{SU}	Setup time from command receipt to ready to transmit	100	_	_	ns	
I ² C Ac	I ² C Addressing							
MPL0	15A2 uses 7-bit addressing, do	oes not ac	knowledge the general call address 0000000. Slav	ve address ha	ıs been se	et to 0x60 o	or 1100000.	
5 5								

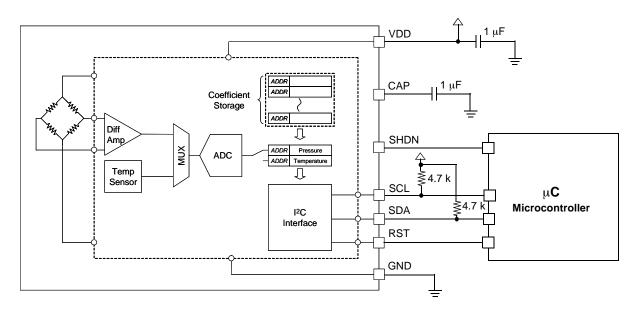


Figure 1. Block Diagram

Compensation

The 10-bit compensated pressure output, Pcomp, is calculated as follows:

Pcomp = a0 + (b1 + Padc + c12*Tadc) * Padc + (b2 + Tadc) * Tadc

Where:

Padc is the 10-bit pressure output of the MPL015A2 ADC,

Tadc is the 10-bit temperature output of the MPL015A2 ADC,

a0 is the pressure offset coefficient,

b1 is the pressure sensitivity coefficient,

c12 is the coefficient for temperature sensitivity coefficient (TCS),

b2 is the 1st order temperature offset coefficient (TCO),

Ideally, Pcomp will produce a value of 0 with an input pressure of 50 kPa and will produce a full-scale value of 1023 with an input pressure of 115 kPa.

Coefficient Bit-Width Specs

The table below specifies the initial coefficient bit-width specs for the compensation algorithm.

	Total Coeff. Bits					
	a0	b1	b2	c12	Bits	
Total Bits	16	16	16	14	62	
Sign Bits	1	1	1	1		
Integer Bits	12	2	1	0		
Fractional Bits	4	13	14	13		
dec pt zero pad	_	_	_	9		

^{*} Factory reserves the option to make these values = 0.

Example Binary Format Definitions:

1. Sign = 0, Integer Bits = 8, Fractional Bits = 4: Coeff =
$$S I_7 I_6 I_5 I_4 I_3 I_2 I_1 I_0 F_3 F_2 F_1 F_0$$

2. Sign = 1, Integer Bits = 4, Fractional Bits = 7: Coeff =
$$S I_3 I_2 I_1 I_0$$
, $F_6 F_5 F_4 F_3 F_2 F_1 F_0$

3. Sign = 0, Integer Bits = 0, Fractional Bits = 6, dec pt zero pad = 2 : Coeff =
$$S \cdot 0 \cdot 0 \cdot 0 \cdot F_5 \cdot F_4 \cdot F_3 \cdot F_2 \cdot F_1 \cdot F_0 \cdot F_3 \cdot F_4 \cdot F_3 \cdot F_2 \cdot F_1 \cdot F_0 \cdot F_3 \cdot F_4 \cdot F_3 \cdot F_3 \cdot F_4 \cdot F_3 \cdot F_3 \cdot F_4 \cdot F_$$

NOTE: Negative coefficients (Sign = 1) are coded in 2's complement notation.

Coefficient Address Map

Address	Coefficient
\$04	a0 MS Byte
\$05	a0 LS Byte
\$06	b1 MS Byte
\$07	b1 LS Byte
\$08	b2 MS Byte
\$09	b2 LS Byte
\$0A	c12 MS Byte
\$0B	c12 LS Byte

For coefficients with less than 16 bits, the lower LSBs are zero. For example, c14 is 14 bits and is stored into 2 bytes as follows:

$$\texttt{c14 MS byte} = \texttt{c14}[\texttt{10:3}] = [\texttt{c14}_{\texttt{b13}} \, , \, \texttt{c14}_{\texttt{b12}} \, , \, \texttt{c14}_{\texttt{b11}} \, , \, \texttt{c14}_{\texttt{b10}} \, , \, \texttt{c14}_{\texttt{b9}} \, , \, \texttt{c14}_{\texttt{b8}} \, , \, \texttt{c14}_{\texttt{b7}} \, , \, \texttt{c14}_{\texttt{b6}}] \\ \texttt{c14 LS byte} = \texttt{c14}[\texttt{2:0}] \, \& \, \text{``00000''} = [\texttt{c14}_{\texttt{b5}} \, , \, \texttt{c14}_{\texttt{b4}} \, , \, \texttt{c14}_{\texttt{b3}} \, , \, \texttt{c14}_{\texttt{b2}} \, , \, \texttt{c14}_{\texttt{b1}} \, , \, \texttt{c14}_{\texttt{b0}} \, , \, \texttt{0} \, , \, \texttt{0}] \\$$

Solder Recommendations

- 1. Use SAC solder alloy (i.e., Sn-Ag-Cu) with a melting point of about 217°C. It is recommended to use SAC305 (i.e., Sn-3.0 wt.% Ag-0.5 wt.% Cu).
- 2. Reflow
 - Ramp up rate: 2 to 3 C/s.
 - Preheat flat (soak): 110 to 130s.
 - Reflow peak temperature: 250°C to 260°C (depends on exact SAC alloy composition).
 - Time above 217°C: 40 to 90s (depends on board type, thermal mass of the board/quantities in the reflow).
 - Ramp down: 5 to 6 C/s.
 - Using an inert reflow environment (with O2 level about 5 to 15 ppm).

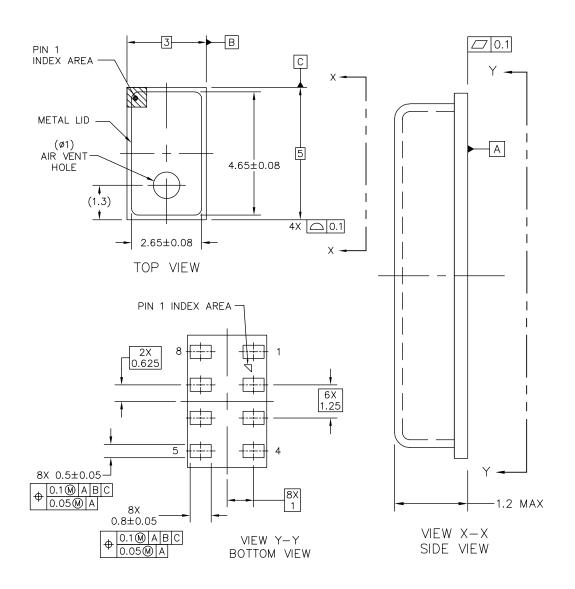
NOTE: The stress level and signal offset of the device also depends on the board type, board core material, board thickness and metal finishing of the board.

Handling Recommendations

It is recommended to handle the MPL015A2 pressure sensor with a vacuum pick and place tool. Sharp objects utilized to move the MPL015A2 pressure sensor increase the possibility of damage via a foreign object/tool into the small exposed port.

The sensor die is sensitive to light exposure. Direct light exposure through the port hole can lead to varied accuracy of pressure measurement. Avoid such exposure to the port during normal operation.

PACKAGE DIMENSIONS



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TITLE: LGA 8 I/O,	DOC	DOCUMENT NO: 98ASA10829D		REV: A	
3 X 5 X 1.25 PITC	CAS	CASE NUMBER: 2015-02 10 MAR 201			
SENSOR 1.2MAX MM	PKG STAI	NDARD: NO	DN-JEDEC		

CASE 2015-02 ISSUE A LGA PACKAGE

PACKAGE DIMENSIONS

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

3. STYLE:
PIN 1: VDD
PIN 2: CAP
PIN 3: GND
PIN 4: SHDN PIN 5: CS PIN 6: DOUT PIN 7: DIN PIN 8: SCLK

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LGA 8 I/O, 3 X 5 X 1.25 PITCH SENSOR 2.0MM PKG			DOCUMENT NO	REV: A		
			CASE NUMBER: 2015-02 14 APR 2009			
			STANDARD: NO	N-JEDEC		

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MPL015A2

How to Reach Us:

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USA/Europe or Locations Not Listed:

Freescale Semiconductor, Inc. Technical Information Center, EL516 2100 East Elliot Road Tempe, Arizona 85284 1-800-521-6274 or +1-480-768-2130 www.freescale.com/support

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH Technical Information Center Schatzbogen 7 81829 Muenchen, Germany +44 1296 380 456 (English) +46 8 52200080 (English) +49 89 92103 559 (German) +33 1 69 35 48 48 (French) www.freescale.com/support

Japan:

Freescale Semiconductor Japan Ltd. Headquarters ARCO Tower 15F 1-8-1, Shimo-Meguro, Meguro-ku, Tokyo 153-0064 Japan 0120 191014 or +81 3 5437 9125 support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor China Ltd. Exchange Building 23F No. 118 Jianguo Road Chaoyang District Beijing 100022 China +86 010 5879 8000 support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center 1-800-441-2447 or +1-303-675-2140 Fax: +1-303-675-2150 LDCForFreescaleSemiconductor@hibbertgroup.com

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